■ MN101D10F , MN101D10G

Туре	MN101D10F	MN101D10G				
ROM (×8-bit)	96 K	128 K				
RAM (×8-bit)	2.5 K	3.5 K				
Package	QFP100-P-18	818B *Lead-free				
Minimum Instruction Execution Time	With main clock operated 0.1397 μs (at 4.0 V to 5.5 V 71.5 μs (at 2.7 V to 5.5 V When sub-clock operated 61 μs (at 2.5 V to 5.5 V, 3	fixed to 14.32 MHz internal frequency division)				
Interrupts	• RESET • Runaway • External 0 • External 1 • External 1 • Timer 0 • Timer 1 • Timer 2 • Timer 3 • Timer 6 • Cylinder(Drum) FG • Servo V-sync • Synchronous 6 • Serial 1 • Serial 2 • PWM 4 • OSDV-sync	• Capstan FG • Control • HSW				
Timer Counter	-	•				
	Timer counter 1: 8-bit × 1 (timer function, linear timer of Clock source	requency; CTL signal				
W\		equency) stem clock frequency unter 2; input of CTL specified edge; underflow of timer 2 unter; coincidence of timer 2 shift register with timer 2 shi				
	Timer counter 3: 16-bit × 1 (timer function, generation of Clock source	lock frequency				
	Timer counter 5: 19-bit × 1 (watchdog, stable oscillation Clock source					
	Timer counter 6: 16-bit × 1 (clock function [max. 2 s]) Clock source	clock frequency				
Serial Interface	Serial 1: 8-bit × 1 (synchronous type/remote control tran (transfer direction of MSB/LSB selectable, start conditi	1/128, 1/256 of system clock frequency; NSBT0 pin input insmission) ion function) 1/128, 1/256 of system clock frequency; 2-division timer input				
	Serial 2: 8-bit × 1 (I ² C) (master transmission/reception, Clock source	slave transmission/reception)				

Panasonic

www.Batasha.et4U.com

MN101D10F, MN101D10G \square

OSD		Display mode Applicable broadcasting system		:	menu(intermal synchronized) display, superimpose(externally synchronized) display			
				:	NTSC, PAL, PAL-M, PAL-N			
		Screen configuration		:	24 characters \times 2n rows (n = 1 to 6)			
		Character type Character size Enlarged characters Character interpolation Line background color		:	max. 256 character types (variable, include special characters)			
				:	12 × 18 dots (vertical direction: 1 dot for 2H at not enlargement) each × 2 settings in horizontal and vertical none 8-hue settable in the row unit at menu display 8 gradations settable in the row unit			
				:				
				:				
				:				
			Line background intensity					
		Screen background color: Character color Character intensity Border function Border brightness		:	8-huesettable at menu display white 8 gradations settable in the row unit 1-dot border in 8 directions 4 gradations settable in the row unit			
				:				
				:				
				:				
				:				
			Blinking Inverted character		none (covered by software)			
		Inver			settable in the character unit			
		Halftone		:	none			
	Input		İ	:	composite video signal input (output level: 1 V[p-p] / 2 V[p-p])			
		Clamp method Output		:	sync tip clamp, clamp level in 4 levels			
				:	composite video output			
	•		Measure against image fluctuation		built-in AFC circuit			
		Dot o	clock	:	1/2 of OSC oscillation clock (automatic phase adjustment)			
		MES	ECAM compatibility	:	Subcarrier leak function for superimpose display			
XDS		Built	-in U.S. closed caption data	slicer (optional 1 line data can be extracted.)			
ROM Correction	1 WW		ecting address designation: ection method: correction pr		addresses possible being saved in internal RAM			
I/O Pins	I/O	76	• Common use: 56					
	Input	1	• Common use: 1					
A/D Inputs		8-bit	× 12-ch. (without S/H)					
PWM		13-bi	it × 2-ch. (at repetition cycle	e 572 μs	at 14.32 MHz),			
		8-bit \times 1-ch. (at repetition cycle 35.7 μ s, 0.572 ms, 1.14 ms, 2.29 ms at 14.32 MHz)						
ICB		16-h	it × 2-ch (Sneed system)					
ICR			it \times 2-ch.(Speed system),					
		18-bi	$it \times 4$ -ch.(Phase system)	, 1 D	CTI v.1)			
OCR		18-bi	it × 4-ch.(Phase system) it × 3 (Synchronous output >					
		18-bi	it × 4-ch.(Phase system) it × 3 (Synchronous output > te output (PTO) VLP pin; C	TL inpu	CTL × 1) t;Capstan FG input; Cylinder(Drum) PG/FG inputs; HSW output; amp; output of 1/4 OSC oscillation clock (1 V[p-p])			

See the next page for electrical characteristics, pin assignment and support tool.

MAD00043BEM Panasonic Www.DataSheet4U.com

Electrical Characteristics

Supply current

Parameter	Symbol	Condition	Limit			Unit
i arameter	Syllibol	Condition		typ	max	Ullit
	IDD1	14.32 MHz operation without load, VDD = 5 V		50	100	mA
Operating augusts augreent	IDD2	1/1024 of 14.32 MHz operation without load, VDD = 2.7 V		2	5	mA
Operating supply current	IDD3	Stop of 14.32 MHz oscillation, VDD = 2.7 V		50	100	μA
		32 kHz oscillation operation without load		30	100	
Supply current at STOP	IDSP	Stop of oscillation without load, VDD = 5 V, Ta = 55 °C			10	μА
	IDHT0	14.32 MHz oscillation without load, VDD = 5 V		5	15	mA
Supply current at HALT	IDIIT1	Stop of 14.32 MHz oscillation, VDD = 2.7 V		5 20	20	۸
	IDHT1	32 kHz oscillation operation without load)	20	μΑ

 $(Ta = 25 \, ^{\circ}C \pm 2 \, ^{\circ}C , VSS = 0 \, V)$

A/D Converter Performance

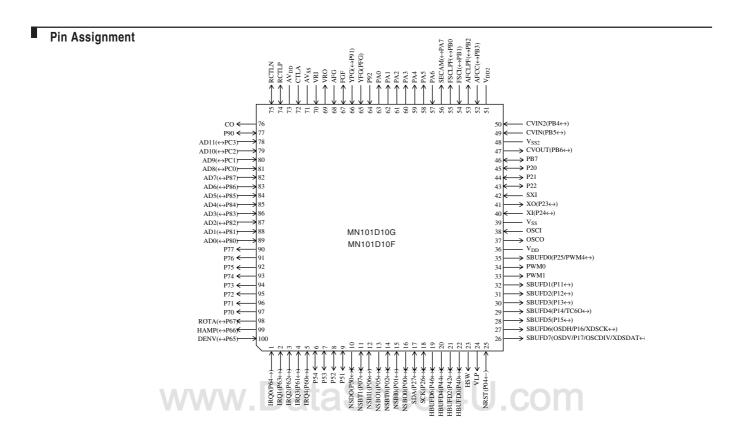
Parameter	Symbol	Condition		Unit		
raidilletei	Syllibol	Condition	min	typ		
Conversion relative error	ΔNLAD				± 3	LSB
A/D Conversion Time	tAD	fosc = 14.32 MHz	m	8		μs
Analog Input Voltage		Jataonoot 10.001			5	V

 $(Ta = 25 \ ^{\circ}\text{C} \pm 2 \ ^{\circ}\text{C} \ , \text{VDD} = 5.0 \ \text{V}, \ \text{VSS} = 0 \ \text{V})$

Panasonic

www.DataSheret4U.com

MN101D10F, MN101D10G □



QFP100-P-1818B *Lead-free

Support Tool

In-circuit Emulator	PX-ICE101C / D + PX-PRB101D10-QFP100-P-1818B-CN-M		
Flash Memory Built-in Type	Туре	MN101DF10GAF	
	ROM (× 8-bit)	128 K	
	RAM (× 8-bit)	4 K	
	Minimum instruction execution time	0.1397 μs (at 4.0 V to 5.5 V, 14.32 MHz)	
		$71.5~\mu s$ (at $2.7~V$ to $5.5~V,$ fixed to $14.32~MHz$ internal division)	
		$61~\mu s$ (at 2.5 V to 5.5 V, 32.768 kHz)	
	Package	QFP100-P-1818B *Lead-free	

MAD00043BEM Panasonic www.DataSheet4U.com

Request for your special attention and precautions in using the technical information and semiconductors described in this material

- (1) An export permit needs to be obtained from the competent authorities of the Japanese Government if any of the products or technical information described in this material and controlled under the "Foreign Exchange and Foreign Trade Law" is to be exported or taken out of Japan.
- (2) The technical information described in this material is limited to showing representative characteristics and applied circuits examples of the products. It neither warrants non-infringement of intellectual property right or any other rights owned by our company or a third party, nor grants any license.
- (3) We are not liable for the infringement of rights owned by a third party arising out of the use of the technical information as described in this material.
- (4) The products described in this material are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).

Consult our sales staff in advance for information on the following applications:

- Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
- Any applications other than the standard applications intended.
- (5) The products and product specifications described in this material are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (6) When designing your equipment, comply with the guaranteed values, in particular those of maximum rating, the range of operating power supply voltage, and heat radiation characteristics. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (7) When using products for which damp-proof packing is required, observe the conditions (including shelf life and amount of time let standing of unsealed items) agreed upon when specification sheets are individually exchanged.
- (8) This material may be not reprinted or reproduced whether wholly or partially, without the prior written permission of Matsushita Electric Industrial Co., Ltd.

www.DataSheet4U.com